This Sheet Has Been Replaced

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ABSTRACT

LEAD FRAME TAPING APPARATUS AND TAPING METHOD

In a lead frame taping apparatus and a method thereof, a plurality of punching portions are provided and each punching portion concurrently attaches a tape to at least two lead frames. Also, the tape can be continuously attached to the different kinds of a lead frame without the exchange of molds by differing the operation time of each punching portion. Further, a taping detecting sensor is provided to detect the attachment of the tape at the lead frame. Therefore, productivity is increased while saving labor and inferior products can be accurately detected.